# NST1009XV6T1, NST1009XV6T5

# Product Preview

# **Dual General Purpose Transistors**

# **NPN/PNP Dual (Complimentary)**

This transistor is designed for general purpose amplifier applications. It is housed in the SOT-563 which is designed for low power surface mount applications.

- Lead-Free Solder Plating
- Low V<sub>CE(SAT)</sub>, < 175 mV

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	$V_{CEO}$	-60	V
Collector-Base Voltage	$V_{CBO}$	-50	V
Emitter-Base Voltage	V <sub>EBO</sub>	-6.0	V
Collector Current – Continuous	Ic	-100	mAdc

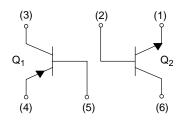
### THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit	
Total Device Dissipation $T_A = 25^{\circ}C$	P <sub>D</sub>	357 (Note 1)	mW	
Derate above 25°C		2.9 (Note 1)	mW/°C	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	350 (Note 1)	°C/W	
Characteristic				
(Both Junctions Heated)	Symbol	Max	Unit	
Total Device Dissipation $T_A = 25^{\circ}C$	$P_{D}$	500	mW	
Derate above 25°C		(Note 1) 4.0 (Note 1)	mW/°C	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	250 (Note 1)	°C/W	
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	

<sup>1.</sup> FR-4 @ Minimum Pad.



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SOT-563 CASE 463A PLASTIC

## **MARKING DIAGRAM**



?? = Specific Device Code

D = Date Code

### **ORDERING INFORMATION**

Device	Package	Shipping†
NST1009XV6T1	SOT-563	4 mm Pitch 4000/Tape & Reel
NST1009XV6T5	SOT-563	2 mm Pitch 8000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

# **NST1009XV6T1, NST1009XV6T5**

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C)

Characteristic	Symbol	Min	Тур	Max	Unit	
Q1: PNP						
Collector–Base Breakdown Voltage (I <sub>C</sub> = -50 μAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-60	_	-	Vdc	
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = -1.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-50	_	-	Vdc	
Emitter–Base Breakdown Voltage (I <sub>E</sub> = –50 μAdc, I <sub>E</sub> = 0)	V <sub>(BR)EBO</sub>	-6.0	_	-	Vdc	
Collector–Base Cutoff Current (V <sub>CB</sub> = -30 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	_	100	nA	
Emitter–Base Cutoff Current (V <sub>EB</sub> = -5.0 Vdc, I <sub>B</sub> = 0)	I <sub>EBO</sub>	-	_	100	nA	
Collector–Emitter Saturation Voltage (Note 4) (I <sub>C</sub> = -50 mAdc, I <sub>B</sub> = -5.0 mAdc)	V <sub>CE(sat)</sub>	-	_	175	mVdc	
DC Current Gain (Note 4) (V <sub>CE</sub> = -6.0 Vdc, I <sub>C</sub> = -1.0 mAdc)	h <sub>FE</sub>	120	_	560	-	
Transition Frequency ( $V_{CE} = -12 \text{ Vdc}, I_{C} = -2.0 \text{ mAdc}, f = 30 \text{ MHz}$ )	f⊤	_	140	-	MHz	
Output Capacitance (V <sub>CB</sub> = -12 Vdc, I <sub>E</sub> = 0 Adc, f = 1 MHz)	C <sub>OB</sub>	_	3.5	-	pF	
Q2: NPN						
Collector-Base Breakdown Voltage ( $I_C = 50 \mu Adc, I_E = 0$ )	V <sub>(BR)CBO</sub>	60	-	-	Vdc	
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = 1.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	50	-	-	Vdc	
Emitter-Base Breakdown Voltage (I <sub>E</sub> = 50 μAdc, I <sub>E</sub> = 0)	V <sub>(BR)EBO</sub>	7.0	-	-	Vdc	
Collector-Base Cutoff Current (V <sub>CB</sub> = 60 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-	100	nA	
Emitter-Base Cutoff Current (V <sub>EB</sub> = 7.0 Vdc, I <sub>B</sub> = 0)	I <sub>EBO</sub>	-	-	100	nA	
Collector-Emitter Saturation Voltage $^{(2)}$ (I <sub>C</sub> = 50 mAdc, I <sub>B</sub> = 5.0 mAdc)	V <sub>CE(sat)</sub>	_	_	175	mVdc	
DC Current Gain <sup>(2)</sup> (V <sub>CE</sub> = 6.0 Vdc, I <sub>C</sub> = 1.0 mAdc)	h <sub>FE</sub>	120	-	560	-	
Transition Frequency (V <sub>CE</sub> = 12 Vdc, I <sub>C</sub> = 2.0 mAdc, f = 30 MHz)	f <sub>T</sub>	-	180	-	MHz	

2.0

pF

 $C_{OB}$ 

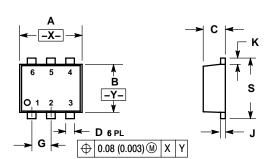
Output Capacitance ( $V_{CB} = 12 \text{ Vdc}$ ,  $I_{C} = 0 \text{ Adc}$ , f = 1 MHz)

Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.
 Pulse Test: Pulse Width ≤ 300 μs, D.C. ≤ 2%.
 Pulse Test: Pulse Width ≤ 300 μs, D.C. ≤ 2%.

# **NST1009XV6T1, NST1009XV6T5**

# PACKAGE DIMENSIONS

**SOT-563, 6 LEAD** CASE 463A-01 ISSUE A



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

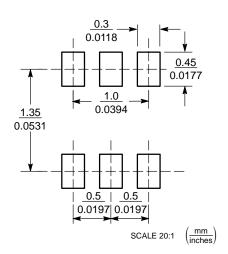
  2. CONTROLLING DIMENSION: MILLIMETERS

  3. MAXIMUM LEAD THICKNESS INCLUDES
  LEAD FINISH THICKNESS. MINIMUM LEAD
  THICKNESS IS THE MINIMUM THICKNESS
  OF BASE MATERIAL.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.50	1.70	0.059	0.067	
В	1.10	1.30	0.043	0.051	
С	0.50	0.60	0.020	0.024	
D	0.17	0.27	0.007	0.011	
G	0.50 BSC		0.020 BSC		
J	0.08	0.18	0.003	0.007	
K	0.10	0.30	0.004	0.012	
S	1.50	1.70	0.059	0.067	

- STYLE 1:
  PIN 1. EMITTER 1
  2. BASE 1
  3. COLLECTOR 2
  4. EMITTER 2
  5. BASE 2
  6. COLLECTOR 1

## **SOLDER FOOTPRINT\***



\*For information on soldering specifications, please refer to our Soldering Reference Manual, SOLDERRM/D.

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